FPGA Core Power Supply

AGND internally tied to PGND on LMZ3 series modules

PMI pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or trace to these pins.

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http://www.ti.com/support
PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.
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Sequencers

Utility 5V Supply
Altera® Stratix® V FPGA Power Solution

Project Title:

Public Release

Assembly Variant: 001

PCB Number: PMP9365

PCB Rev: E1

Texas Instruments

Version control disabled

SVN Rev: PMP9365

Number: Rev: E1

Label Assembly Notes:

1. This Assembly Note is for PCB labels only.

2. These assemblies are ESD sensitive, ESD precautions shall be observed.

3. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

4. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Label Table:

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

PCB Logo:

Texas Instruments

PCB Label:

Size: 0.65" x 0.20"
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